AVAGO
TECHNOLOGIES

PCN: V09-217-475316-0A

Product Change Notice

THIS CHANGE AFFECTS HERMETIC OPTOCOUPLERS ONLY

Issue Date: 07 Sept 2009
HOC217
CAGE Code 50434

Change Type:

Die wafer process change.

Parts Affected:

HCPL-5230
HCPL-5230#100
HCPL-5230#200
HCPL-5230#300
HCPL-5231
HCPL-5231#100
HCPL-5231#200
HCPL-5231#300
HCPL-6230
HCPL-6231
HCPL-6250
HCPL-6251

DSCC SMD NUMBERS:

5962-8876901PA
5962-8876901PC
5962-8876901YA
5962-8876901YC
5962-8876901XA
5962-88769022A
5962-8876903FC

Description and Extent of Change:

After the successful completion of die qualification, Avago Technologies will begin to use IC's fabricated utilizing a process change from a solid planar source predeposition doping to a liquid source predeposition doping. This changes the method of depositing phosphorus onto the wafers.

This change affects commercial and Class H products only. Class K products are not affected at this time. There are no data sheet parameters affected by this change.

Reasons for Change:

Enhanced process uniformity and stability.

Effective Date of Change:

This change will affect product starting with date code 0944, shipping in the November-December 2009 timeframe.
GIDEP Product Chance Notice, Document JL8-C-09-0001A, reflecting this change was published and posted in August 2009. Please contact Debbi Beauchesne at 408.435.2716 (debbi.beauchesne@avagotech.com) if there are any questions or concerns.

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Quality Assurance Manager